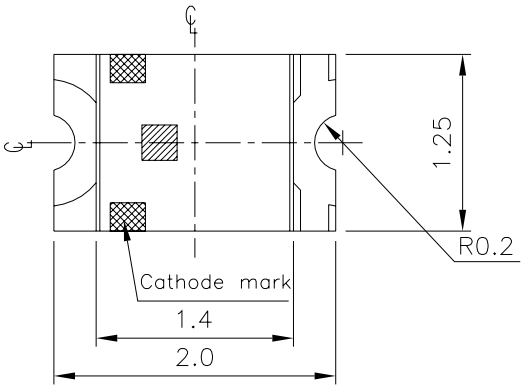
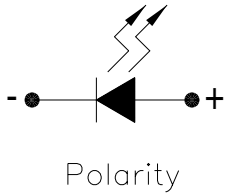
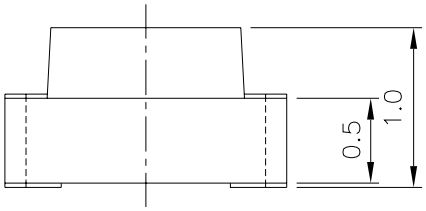
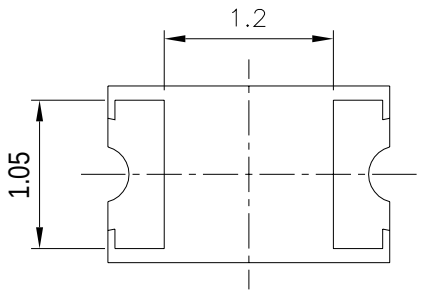
Package Outline Dimensions

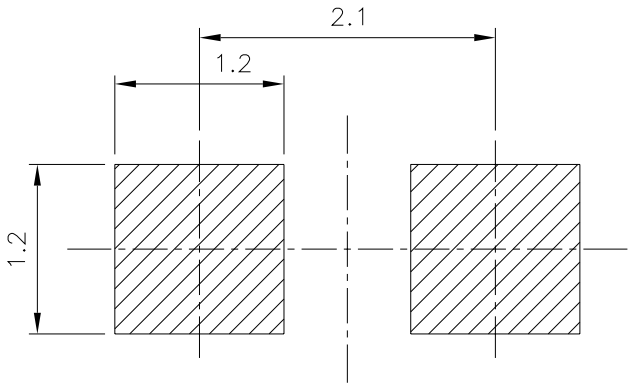






For reflow soldering (Propose)





Note: The tolerances unless mentioned is ±0.1mm, Unit = mm

Absolute Maximum Ratings (Ta=25℃)

Parameter	Symbol	Rating	Unit
Reverse Voltage	V_R	5	V
Forward Current	I_F	25	mA
Peak Forward Current (Duty 1/10 @1KHz)	I_{FP}	100	mA
Power Dissipation	Pd	95	mW
Electrostatic Discharge(HBM)	ESD	150	V
Operating Temperature	Topr	-40 ~ +85	℃
Storage Temperature	Tstg	-40 ~ +90	℃
Soldering Temperature	Tsol	Reflow Soldering : 260 ℃ for 10 sec. Hand Soldering : 350 ℃ for 3 sec.	

Electro-Optical Characteristics (Ta=25℃)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Luminous Intensity	Iv	28.5	-----	72	mcd	I_F=5mA
Viewing Angle	2θ 1/2	-----	150	-----	deg	
Forward Voltage	V_F	2.70	-----	3.15	V	
Reverse Current	I_R	-----	-----	50	μA	V_R=5V

Notes:

1.Tolerance of Luminous Intensity ±11%

2.Tolerance of Forward Voltage ±0.1V

Bin Range Of Luminous Intensity

Bin Code	Min	Max	Unit	Condition
N	28.5	45	mcd	I_F =5mA
P	45	72		

Bin Range Of Forward Voltage

Group	Bin	Min	Max	Unit	Condition
H	15	2.70	2.85	V	I_F =5mA
	16	2.85	3.00		
	17	3.00	3.15		

Notes:

1.Tolerance of Luminous Intensity ±11%

2.Tolerance of Forward Voltage ±0.1V

17-21/W1D-ANPHY/3T

Chromaticity Coordinates Specifications for Bin Grading

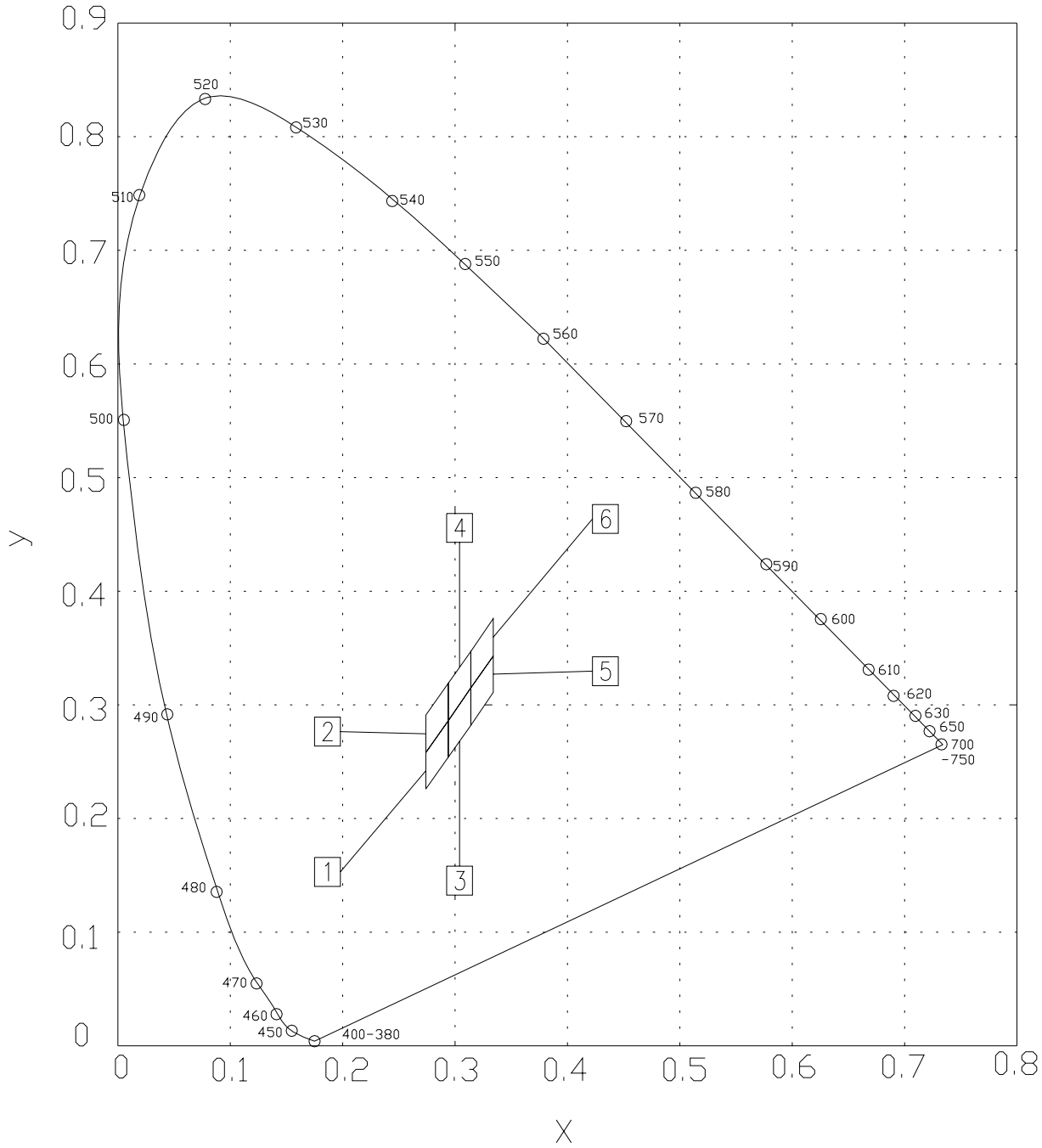
Groups	Bin Code	CIE_x	CIE_ y	Condition
A	1	0.274	0.226	I_F=5mA
		0.274	0.258	
		0.294	0.286	
		0.294	0.254	
	2	0.274	0.258	
		0.274	0.291	
		0.294	0.319	
		0.294	0.286	
	3	0.294	0.254	
		0.294	0.286	
		0.314	0.315	
		0.314	0.282	
	4	0.294	0.286	
		0.294	0.319	
		0.314	0.347	
		0.314	0.315	
	5	0.314	0.282	
		0.314	0.315	
		0.334	0.343	
		0.334	0.311	
	6	0.314	0.315	
		0.314	0.347	
		0.334	0.376	
		0.334	0.343	

Notes:

1.The C.I.E. 1931 chromaticity diagram (Tolerance ±0.01) .

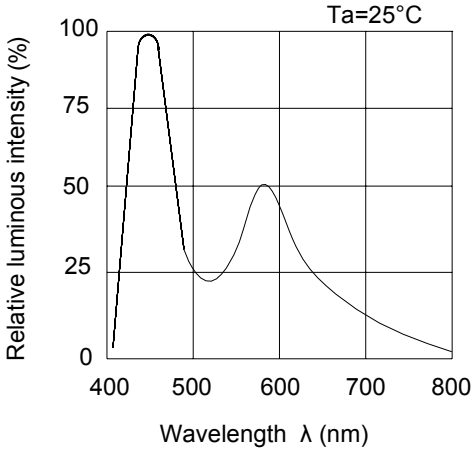
2.The products are sensitive to static electricity and care must be fully taken when handling products.

CIE Chromaticity Diagram

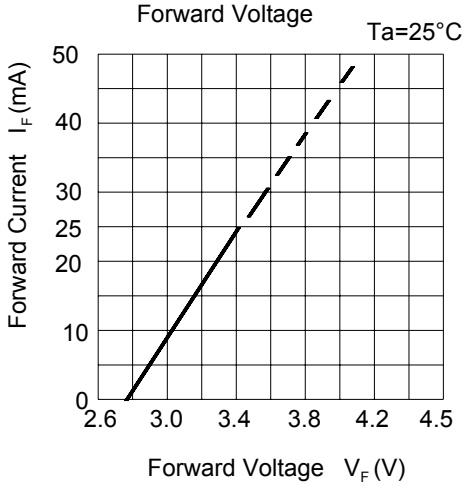


Typical Electro-Optical Characteristics Curves

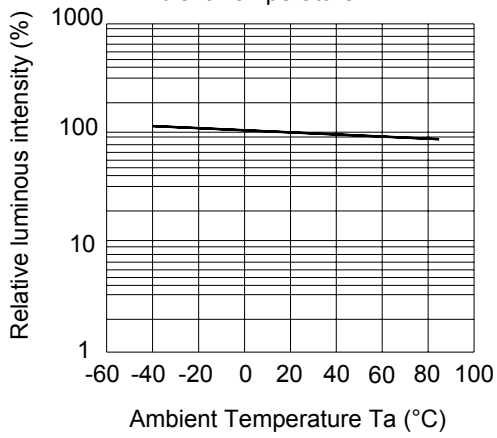
Spectrum Distribution



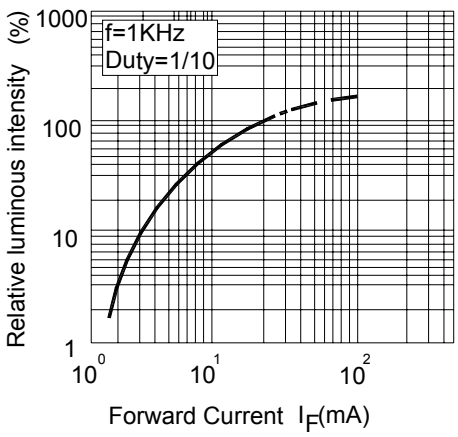
Forward Current vs. Forward Voltage



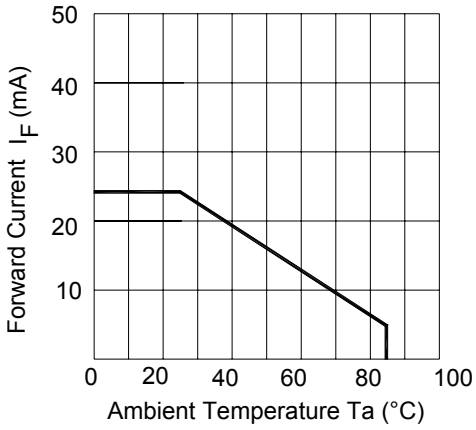
Relative Luminous Intensity vs. Ambient Temperature

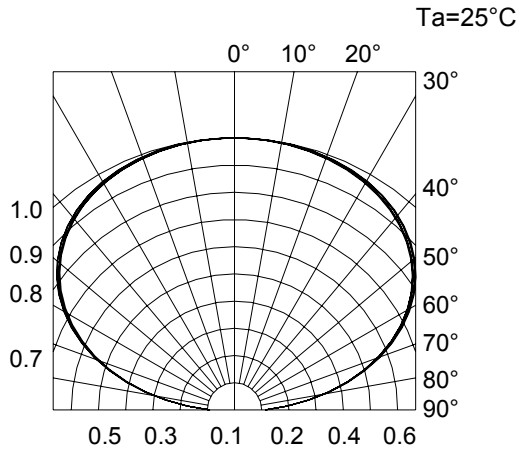


Relative Luminous Intensity vs Forward Current



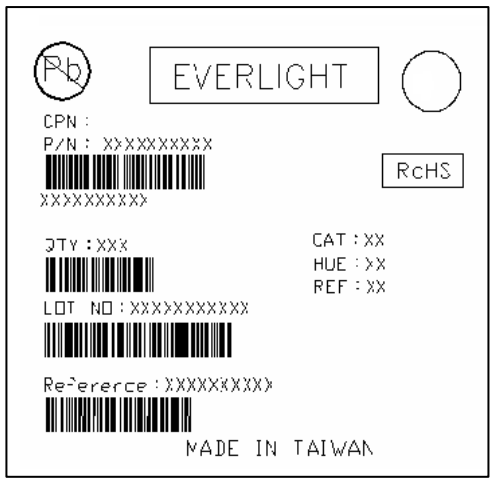
Forward Current Derating Curve



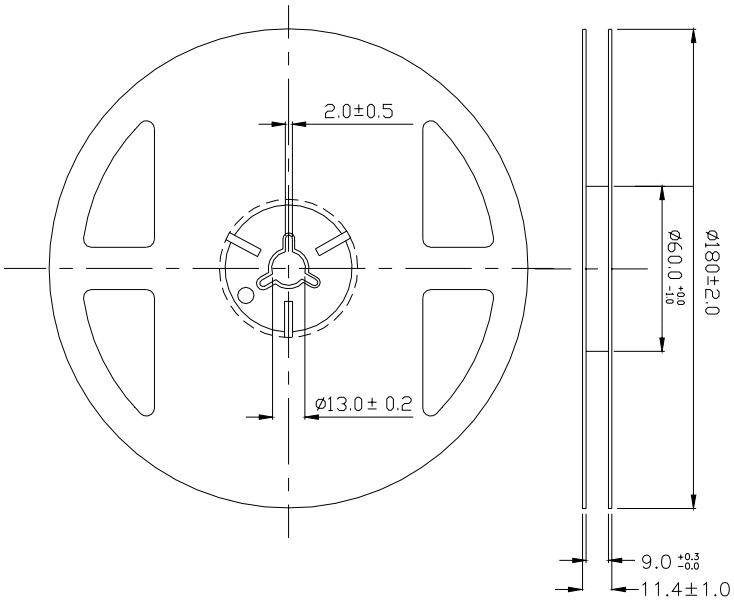


Label explanation

CAT: Luminous Intensity Rank HUE: Chromaticity Coordinates REF: Forward Voltage Rank

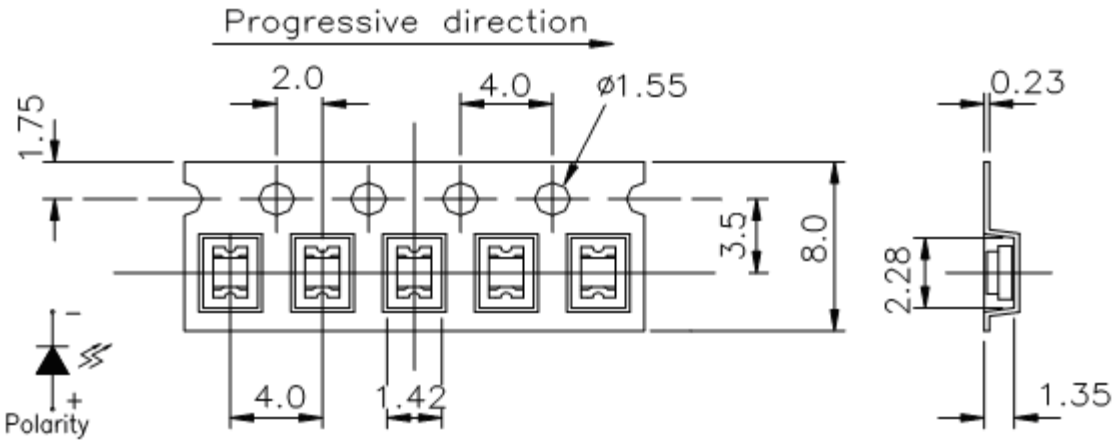


Reel Dimensions



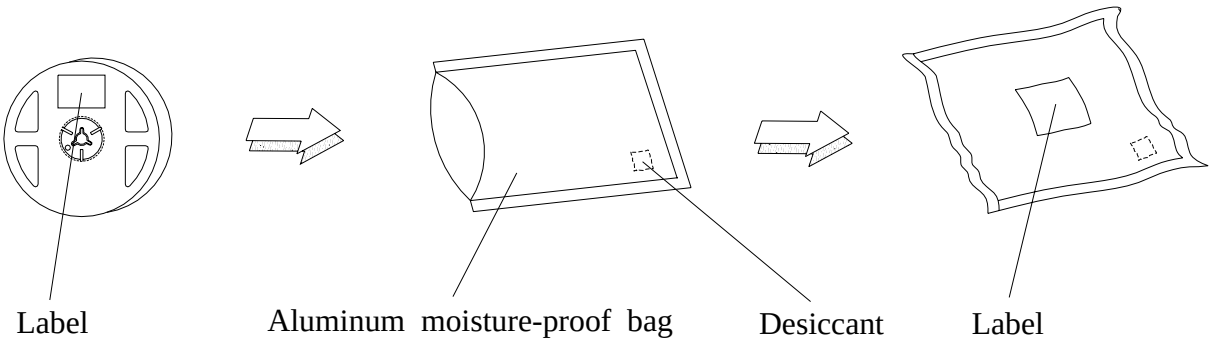
Note: The tolerances unless mentioned is ±0.1mm ,Unit = mm

Carrier Tape Dimensions: Loaded quantity 3000 PCS per reel



Note: The tolerances unless mentioned is ±0.1mm ,Unit = mm

Moisture Resistant Packaging



Reliability Test Items And Conditions

The reliability of products shall be satisfied with items listed below.

Confidence level：90%

LTPD：10%

No.	Items	Test Condition	Test Hours/Cycles	Sample Size	Ac/Re
1	Reflow Soldering	Temp. : 260℃±5℃ Min. 5sec.	6 Min.	22 PCS.	0/1
2	Temperature Cycle	H : +100℃ 15min ∫ 5 min L : -40℃ 15min	300 Cycles	22 PCS.	0/1
3	Thermal Shock	H : +100℃ 5min ∫ 10 sec L : -10℃ 5min	300 Cycles	22 PCS.	0/1
4	High Temperature Storage	Temp. : 100℃	1000 Hrs.	22 PCS.	0/1
5	Low Temperature Storage	Temp. : -40℃	1000 Hrs.	22 PCS.	0/1
6	DC Operating Life	I_F = 20 mA	1000 Hrs.	22 PCS.	0/1
7	High Temperature / High Humidity	85℃/ 85%RH	1000 Hrs.	22 PCS.	0/1

Precautions For Use

1. Over-current-proof

Customer must apply resistors for protection , otherwise slight voltage shift will cause big current change (Burn out will happen).

2. Storage

2.1 Do not open moisture proof bag before the products are ready to use.

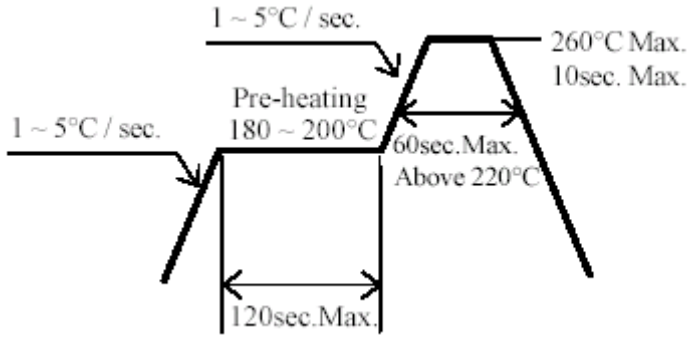
2.2 Before opening the package: The LEDs should be kept at 30℃ or less and 90%RH or less.

2.3 After opening the package: The LED's floor life is 1 year under 30℃ or less and 60% RH or less. If unused LEDs remain, it should be stored in moisture proof packages.

2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.
Baking treatment : 60±5℃ for 24 hours.

3. Soldering Condition

3.1 Pb-free solder temperature profile



3.2 Reflow soldering should not be done more than two times.

3.3 When soldering, do not put stress on the LEDs during heating.

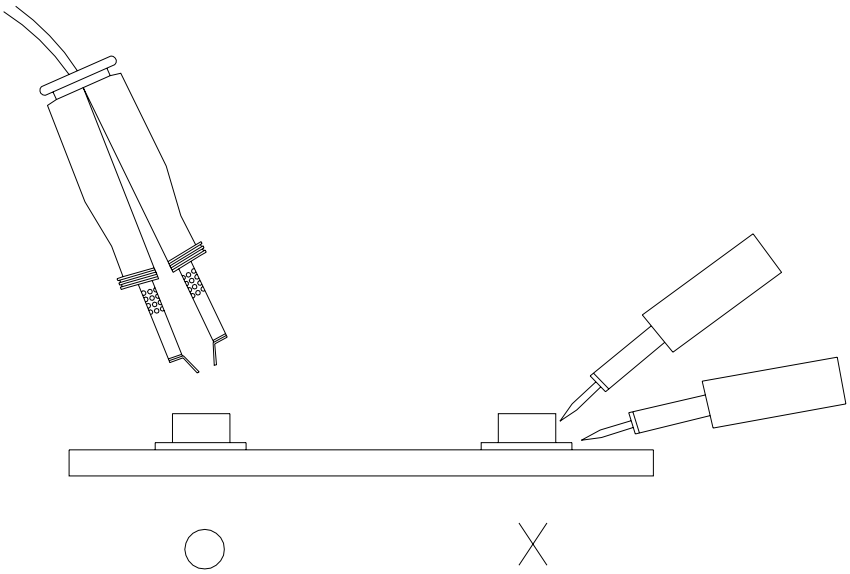
3.4 After soldering, do not warp the circuit board.

4.Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350℃ for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5.Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.



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